



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Features

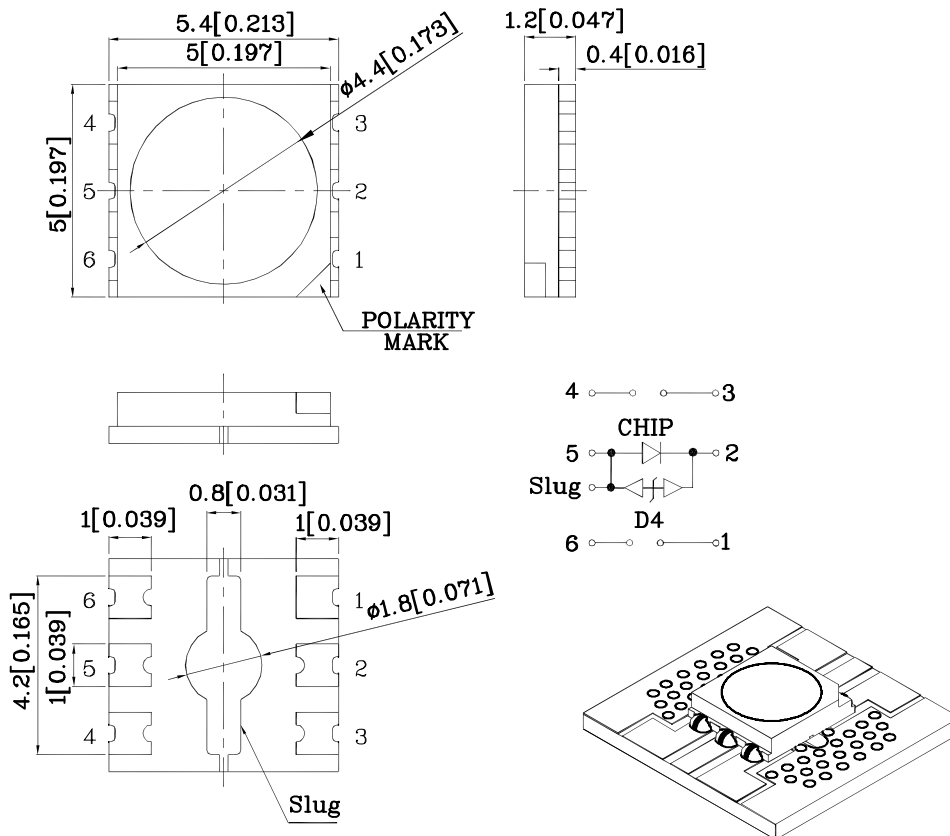
- 5.0mm X 5.0mm X 1.2mm SMD LED
- Zener diode provided for ESD protection
- IR-reflow compatible
- Standard Package: 500pcs / Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



Package Schematics



Notes:

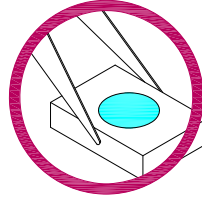
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

Handling Precautions

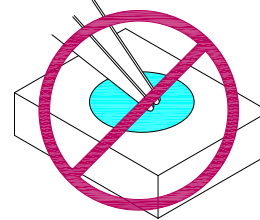
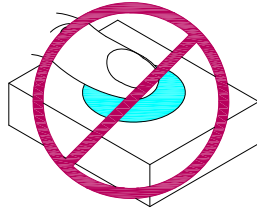
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

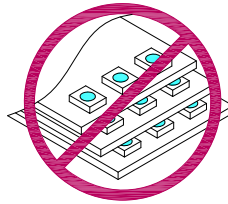
1. Handle the component along the side surfaces by using forceps or appropriate tools.



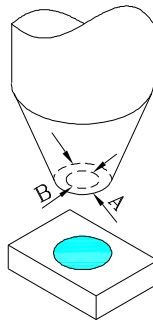
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Part Number	Dice	Lens-color	Luminous Intensity CIE127-2007* (I _F =350mA) [2] cd		Luminous Flux CIE127-2007* (I _F =350mA)[2] lm		Viewing Angle 2 θ 1/2 [1]
			Min.	Typ.	Min.	Typ.	
XZMDH146S	Red (AlGaInP)	Water Clear	5*	7.99*	29*	39.7*	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%. *LEDs are binned according to their luminous flux.
- * Luminous Intensity/Luminous Flux value is in accordance with CIE127-2007 standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit
Power dissipation	P _D	1.05	W
Junction temperature	T _J	110	°C
Reverse Voltage	V _R	5	V
Operating Temperature	T _{op}	-40 To +100	°C
Storage Temperature	T _{stg}	-40 To +110	°C
DC Forward Current [1]	I _F	350	mA
Peak Forward Current [2]	I _{FM}	500	mA
Thermal resistance	R _{th j-a}	62	°C/W
Electrostatic Discharge Threshold (HBM)		8000	V

Notes:

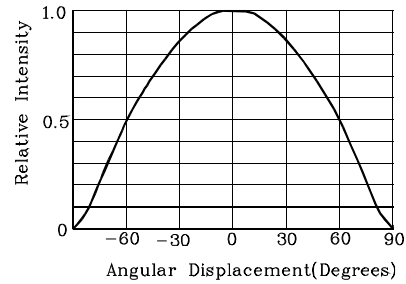
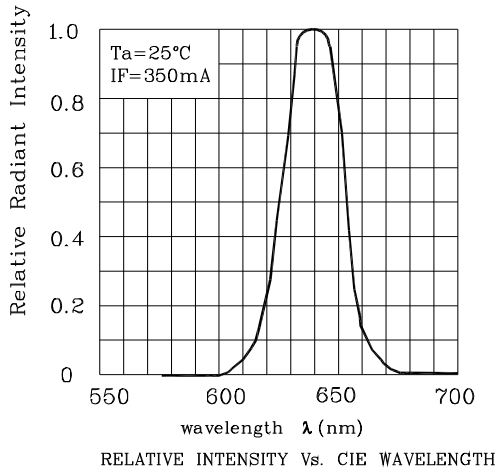
1. Results from mounting on metal core PCB, mounted on pc board-metal core PCB is recommend for lowest thermal resistance.
2. 1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at TA=25°C

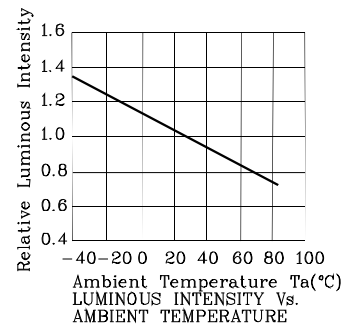
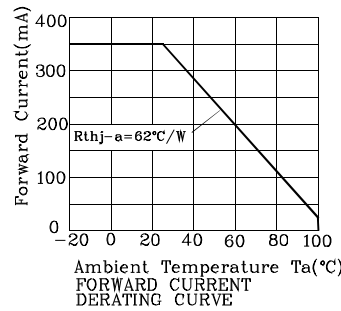
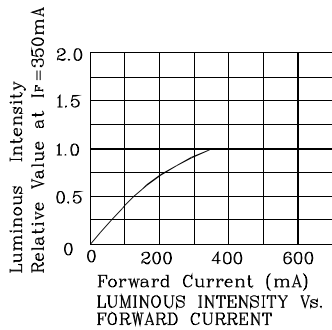
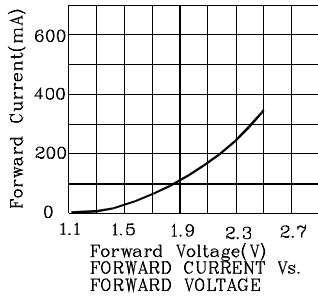
Parameter	Symbol	Value	Unit
Wavelength at peak emission I _F = 350mA CIE127-2007* [Typ.]	λ _{peak}	640*	nm
Dominant Wavelength I _F = 350mA CIE127-2007* [Typ.]	λ _{dom} [1]	625*	nm
Spectral bandwidth at 50% Φ _{REL MAX} I _F = 350mA [Typ.]	Δλ	20	nm
Forward Voltage I _F =350mA [Min.]	V _F [2]	-	V
Forward Voltage I _F =350mA [Typ.]		2.5	
Forward Voltage I _F =350mA [Max.]		3.0	
Allowable Reverse Current [Max.]	I _R	85	mA
Temperature coefficient of λ _{peak} I _F = 350mA, - 10°C ≤ T ≤ 100°C [Typ.]	TCλ _{peak}	0.14	nm/°C
Temperature coefficient of λ _{dom} I _F = 350mA, - 10°C ≤ T ≤ 100°C [Typ.]	TCλ _{dom}	0.12	nm/°C
Temperature coefficient of V _F I _F = 350mA, - 10°C ≤ T ≤ 100°C [Typ.]	TC _V	-3.0	mV/°C

Notes:

1. Wavelength : +/-1nm.
 2. Forward Voltage: +/-0.1V.
- *wavelength value is in accordance with CIE127-2007 standards.

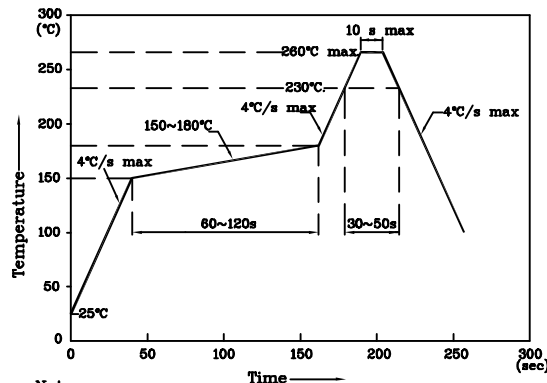


❖ MDH



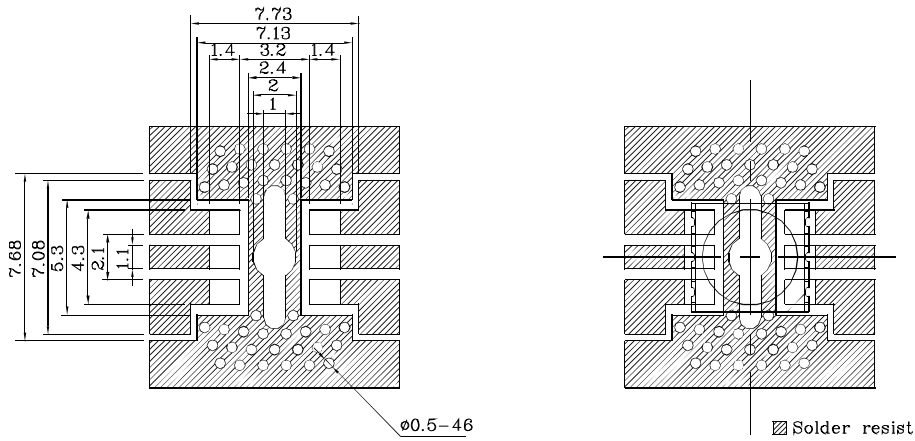
LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

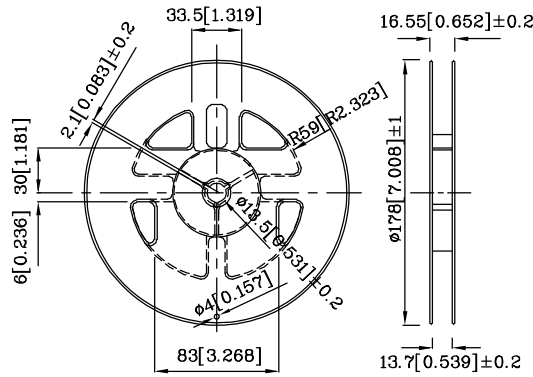


- Notes:
1. Maximum soldering temperature should not exceed 260°C
 2. Recommended reflow temperature: 145°C-260°C
 3. Do not put stress to the epoxy resin during high temperatures conditions

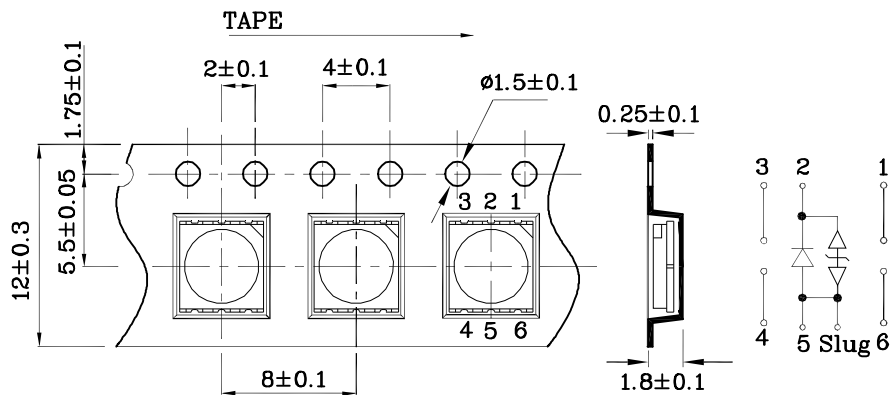
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



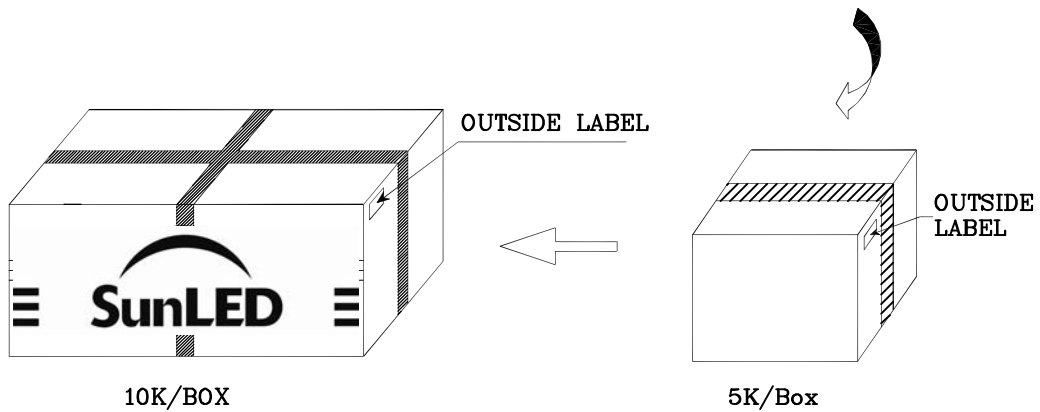
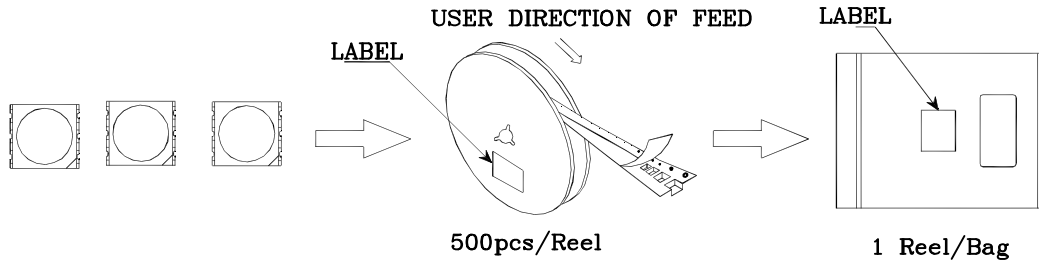
❖ Reel Dimension




❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS






Q.C.

Q C

XX XX XXXX

PASSED

P/NO : XZxxx146x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	

TERMS OF USE

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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